

DEVICE TESTING APPARATUS

This application is a continuation of co-pending Application No. 10/121,592, filed on April 15, 2002, ^{ABN} which is a divisional of Application No.

5 09/448,303, filed on November 24, 1999, now abandoned, the entire contents of which are hereby incorporated by reference and for which priority is claimed under 35 U.S.C. § 120; and this application claims priority of Application Nos. 10-333,864 filed in Japan on November 25, 1998, 10-364,356 filed in Japan on December 22, 1998, and 10-351,357 filed in Japan on December 10, 1998 under 35
10 U.S.C. § 119.

BACKGROUND OF THE INVENTION**1. Field of the Invention**

The present invention relates to a device testing apparatus for testing IC chips and other electronic devices at a predetermined temperature, more
15 particularly relates to a device testing apparatus which accurately controls the temperature of the electronic devices even if the electronic devices generate heat on their own during the testing and thereby enables the electronic devices to be tested at the desired test temperature.

2. Description of the Related Art

20 In the process of production of a semiconductor device etc., a tester is necessary for testing the finally produced IC chip or other device. As one type of such a tester, there is known an apparatus for testing an IC chip at high temperature, ordinary temperature or temperature conditions lower than ordinary temperature. This is because it is guaranteed as one of the features of an IC chip
25 that it operate well as high temperature, ordinary temperature, or low temperature.

In such a tester, the top of the test head is covered by a chamber, the inside is made an air-tight space, an IC chip is conveyed on to the test head, the IC chip is pushed against the test head for connection, and the IC chip is tested while maintaining the inside of the chamber at a certain